Title (en)

WAFER DELIVERY SYSTEM

Title (de)

VERABREICHUNGSSYSTEM AUF DER BASIS VON OBLADEN

Title (fr)

SYSTEME D'APPORT PAR CACHET

Publication

EP 1162988 A1 20011219 (EN)

Application

EP 00917953 A 20000316

Priority

- US 0006772 W 20000316
- US 27082099 A 19990318

Abstract (en)

[origin: WO0054794A1] A primarily grain-based, or other non-sugar carbohydrate-based, wafer (typically disc-shaped and having a diameter of between about 7/8 inch-1 1/2 inch (e.g. about 2.1-3.8 cm) and a thickness of between about 1-2 mm (e.g. about 1/16 inch)) is used as a delivery system for a medicinal treatment or food supplement, preferably a homeopathic remedy, Chinese herb, or a combination of homeopathic medicines and Chinese herbs, with or without other substances. A dry substance comprising the Chinese herb, homeopathic remedy, or mixture of them is mixed with a solvent to produce a mother tincture, the tincture is preferably attenuated, and then the wafer is impregnated with the attenuation, as by soaking the wafer in the solvent containing the dry substance, or spraying the solvent containing the dry substance on the wafer, or incorporating the attenuation in the wafer during wafer production. Then solvent is evaporated, and the wafer is packaged for transport to a patient in need of the treatment or food supplement provided by the attenuation.

IPC 1-7

A61K 35/78; A61K 9/00; A61P 43/00

IPC 8 full level

A23L 1/30 (2006.01); **A61K 9/00** (2006.01); **A61K 36/00** (2006.01); **A61K 36/18** (2006.01); **A61K 36/23** (2006.01); **A61K 36/25** (2006.01); **A61K 36/28** (2006.01); **A61K 36/29** (2006.01); **A61K 36/48** (2006.01); **A61K 36/53** (2006.01); **A61K 36/71** (2006.01); **A61K 36/75** (2006.01); **A61K 36/81** (2006.01); **A61K 41/00** (2006.01); **A61K 47/10** (2006.01); **A61K 47/26** (2006.01); **A61K 47/36** (2006.01); **A61P 3/04** (2006.01); **A61P 15/12** (2006.01); **A61P 25/04** (2006.01); **A61P 25/20** (2006.01); **A61P 27/14** (2006.01); **A61P 43/00** (2006.01)

CPC (source: EP)

A61K 9/0056 (2013.01); **A61K 41/0004** (2013.01); **A61P 3/04** (2017.12); **A61P 15/12** (2017.12); **A61P 25/04** (2017.12); **A61P 25/20** (2017.12); **A61P 27/14** (2017.12); **A61P 43/00** (2017.12)

Citation (search report)

See references of WO 0054794A1

Designated contracting state (EPC)

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